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(12) United States Design Patent

Sato

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(54) **PEDESTAL OF HEAT INSULATING CYLINDER FOR MANUFACTURING SEMICONDUCTOR WAFERS**

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(73) Assignee: **Tokyo Electron Limited**, Minato-Ku (JP)

(**) Term: **14 Years**

(21) Appl. No.: **29/342,850**

(22) Filed: **Sep. 2, 2009**

(30) **Foreign Application Priority Data**

Mar. 6, 2009 (JP) 2009-004985

(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Classification Search** D13/182; 206/454, 711; 118/728, 729; 211/41.18; 432/241, 253, 258

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a pedestal of heat insulating cylinder for manufacturing semiconductor wafers, as shown and described.

DESCRIPTION

FIG. **1** is front perspective view of a pedestal of heat insulating cylinder for manufacturing semiconductor wafers illustrating my new design;

FIG. **2** is a front view thereof;

FIG. **3** is a rear view thereof;

FIG. **4** is a right side view thereof;

FIG. **5** is a left side view thereof;

FIG. **6** is a top plan view thereof;

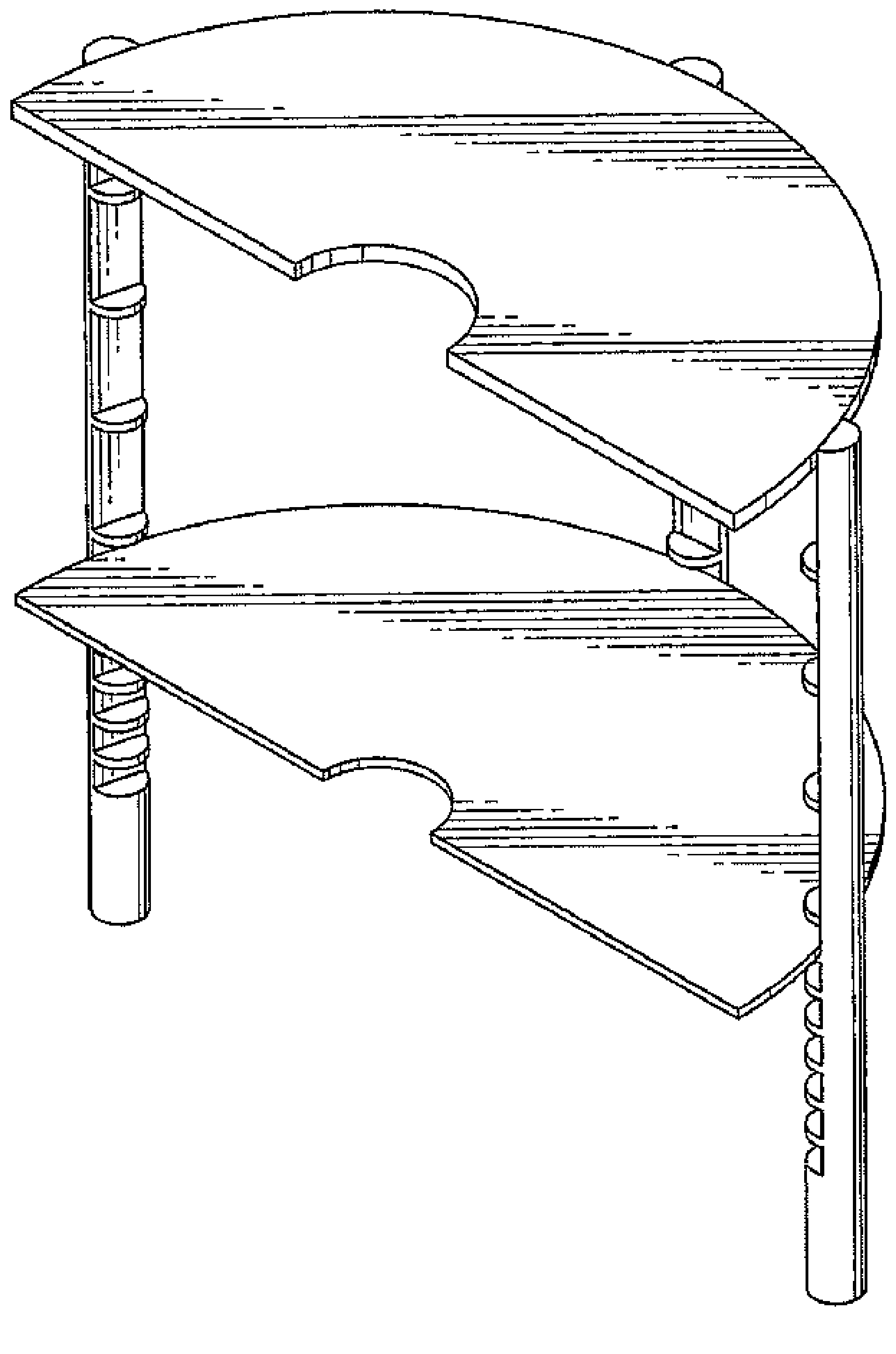
FIG. **7** is a bottom plan view thereof;

FIG. **8** is a cross-sectional view taken through line **8**—**8** of FIG. **2**; and,

FIG. **9** is a front perspective view of a pedestal of heat insulating cylinder for manufacturing semiconductor wafers in use.

The broken lines are shown for illustrative purposes only and form no part of the claimed design.

1 Claim, 7 Drawing Sheets



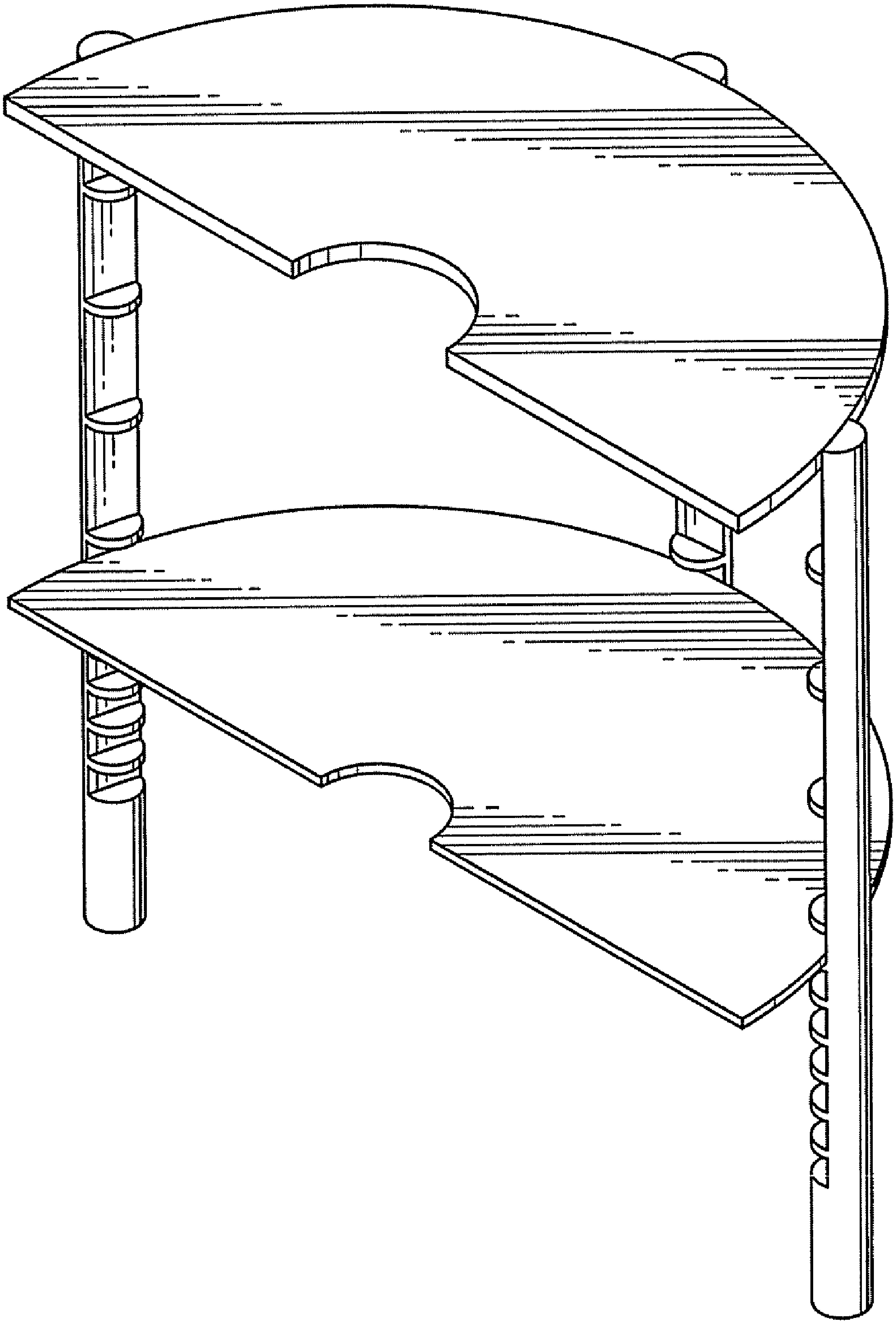


FIG. 1

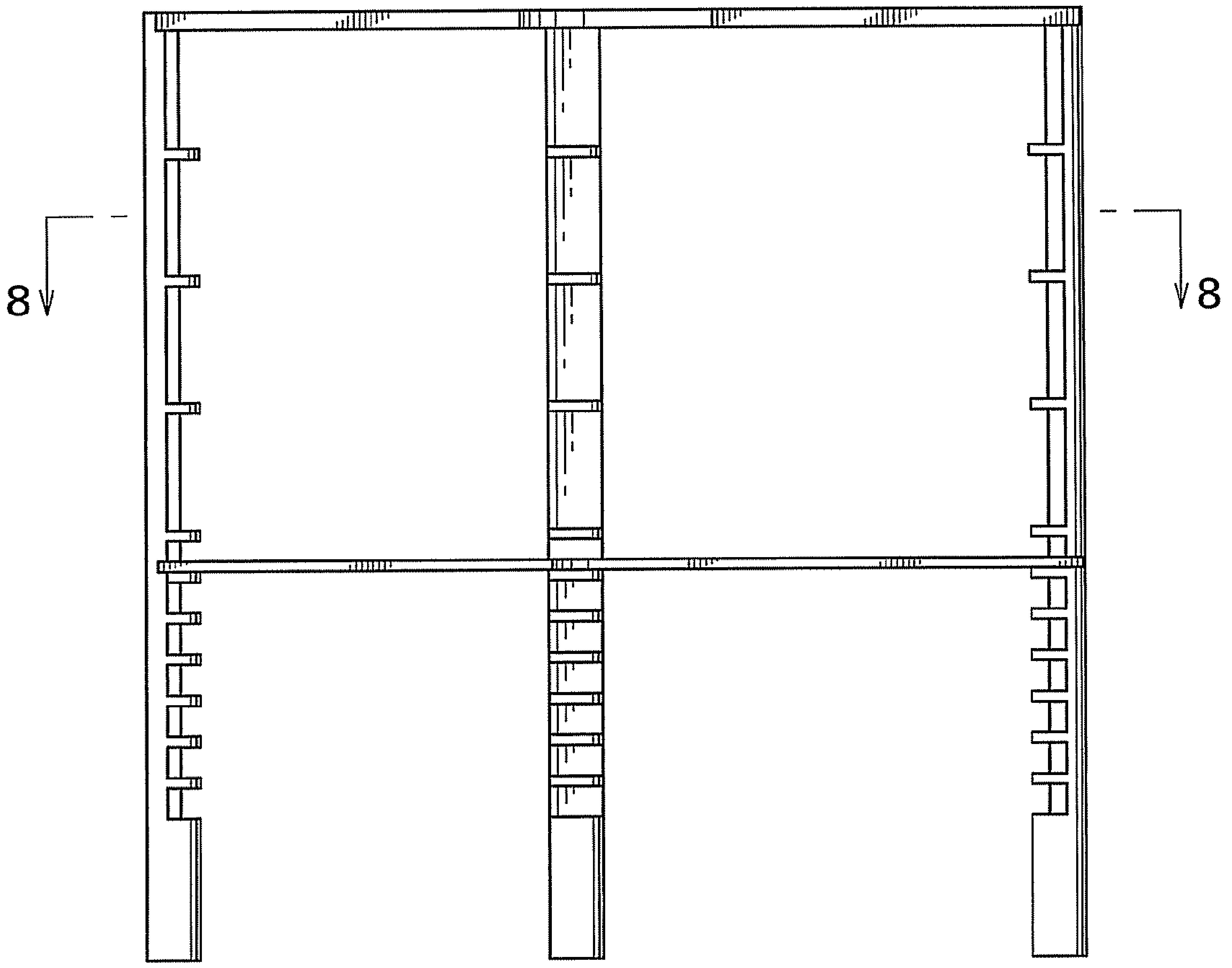


FIG. 2

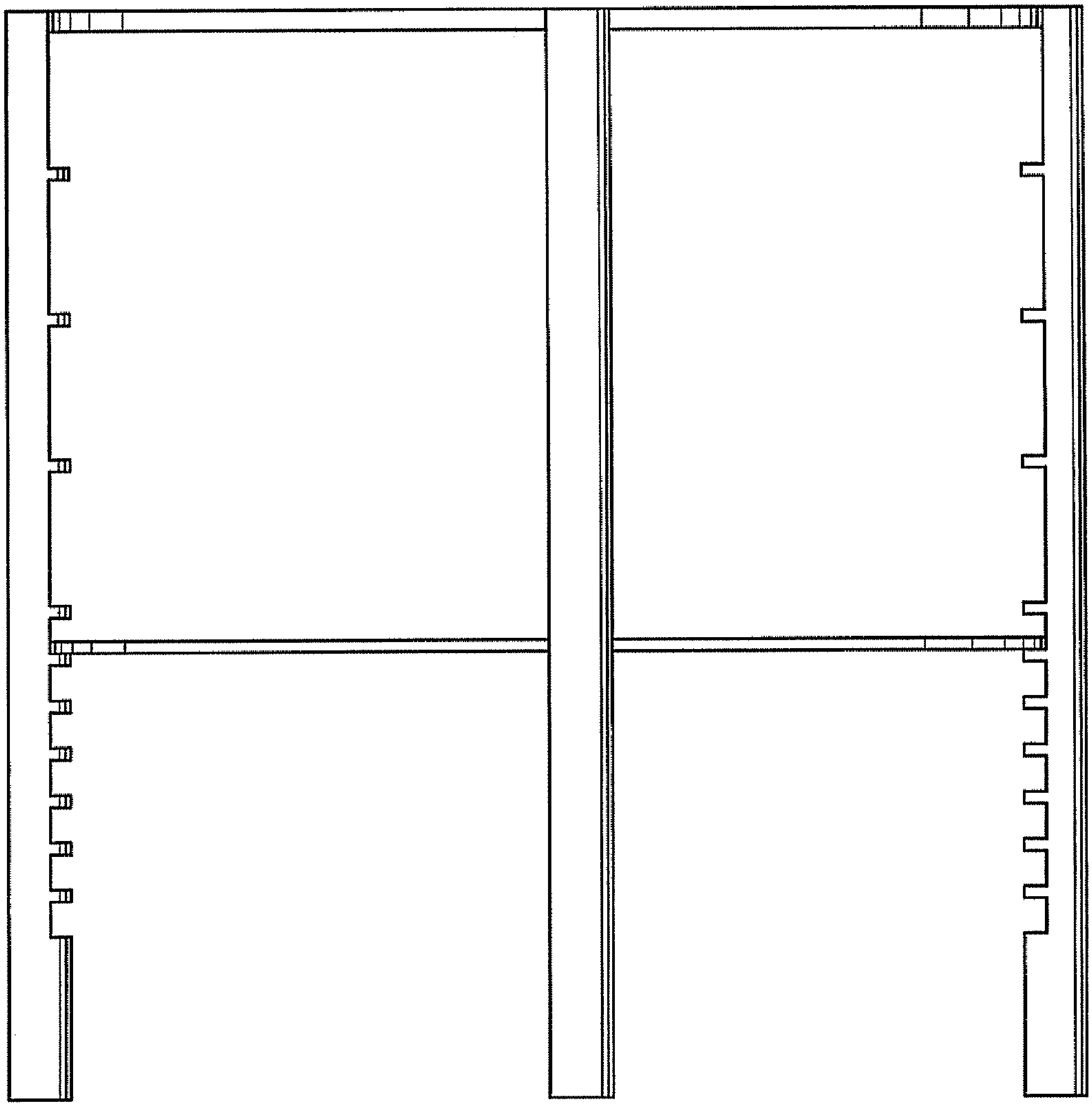


FIG. 3

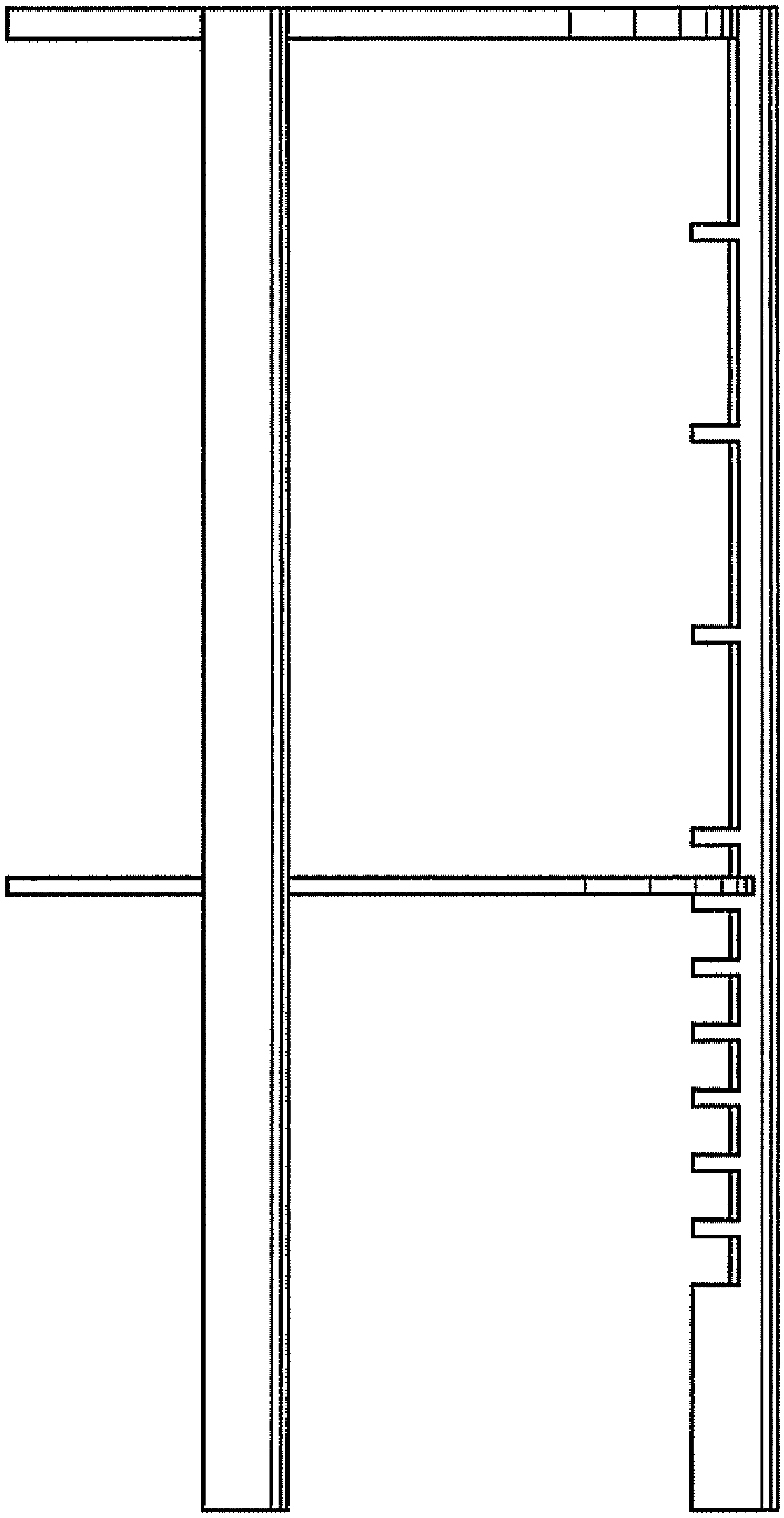


FIG. 4

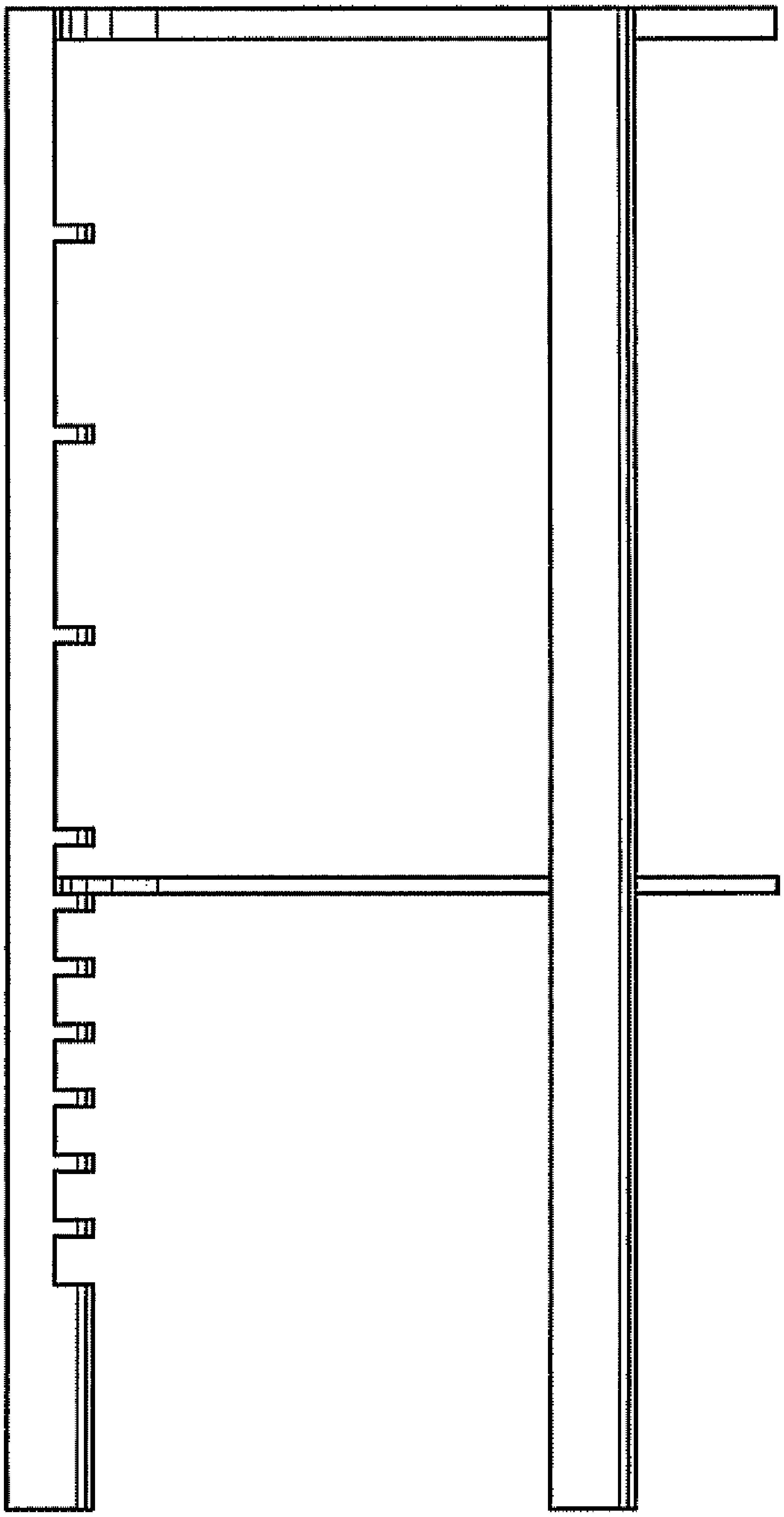


FIG. 5

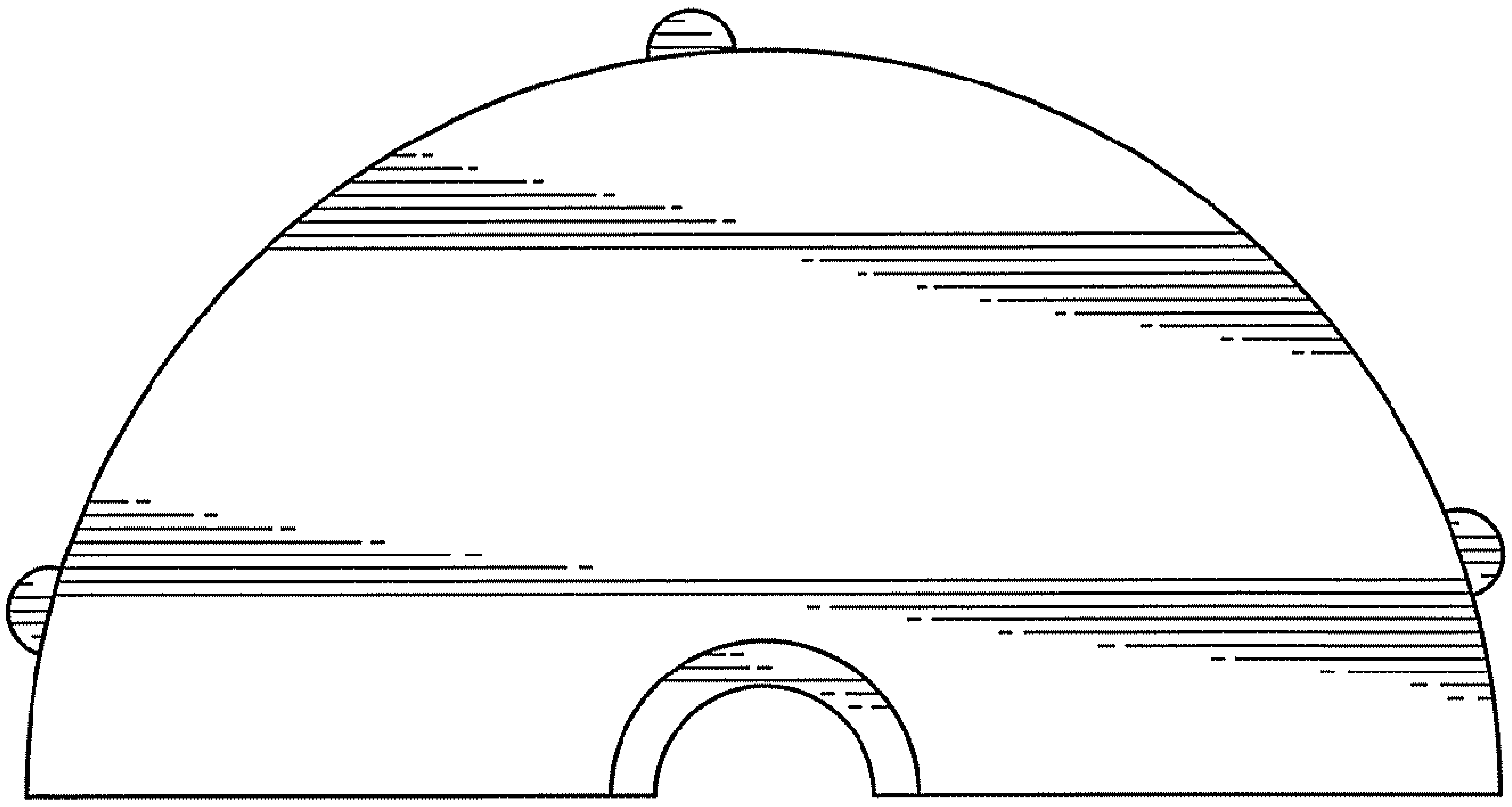


FIG. 6

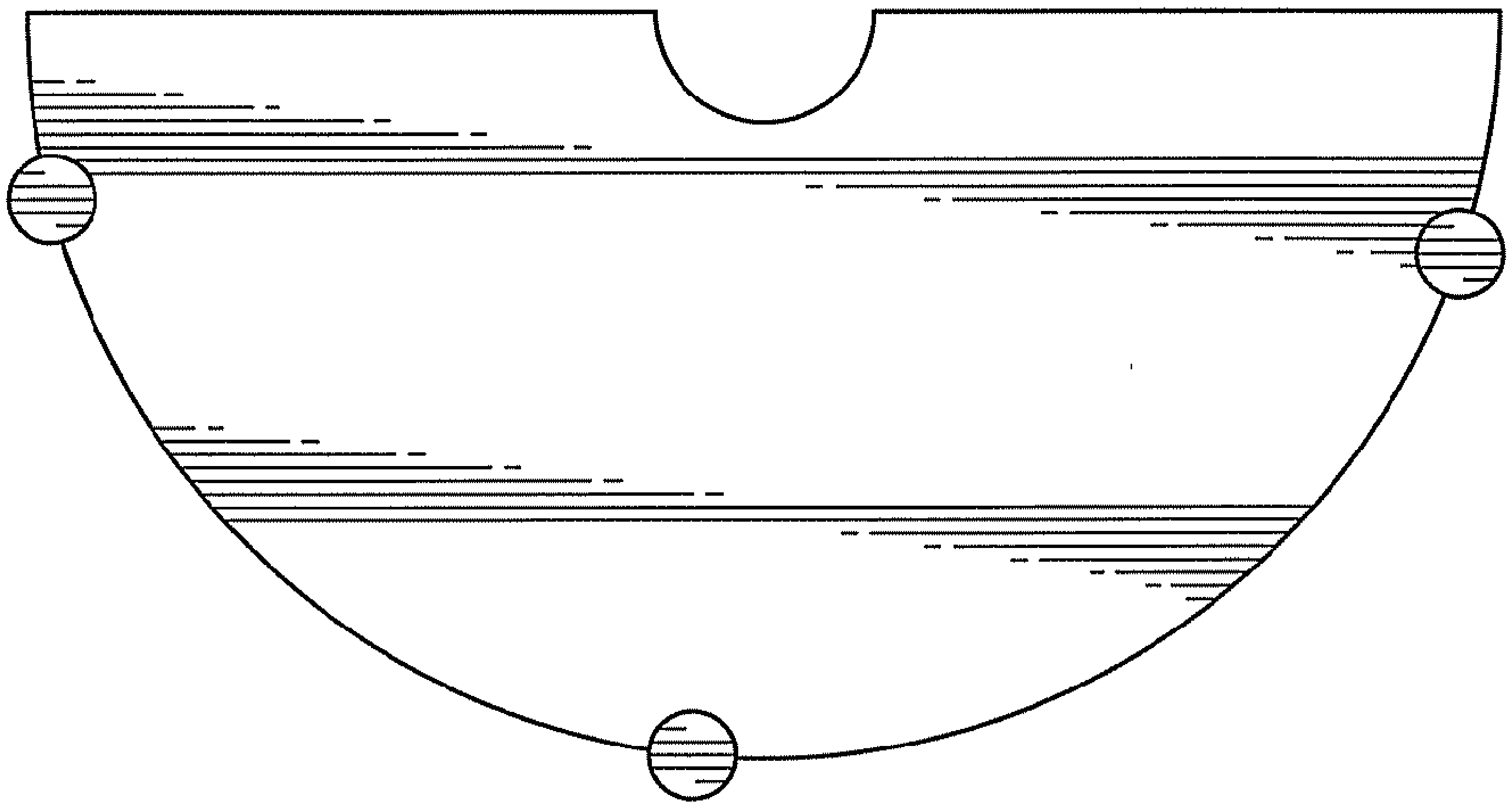


FIG. 7

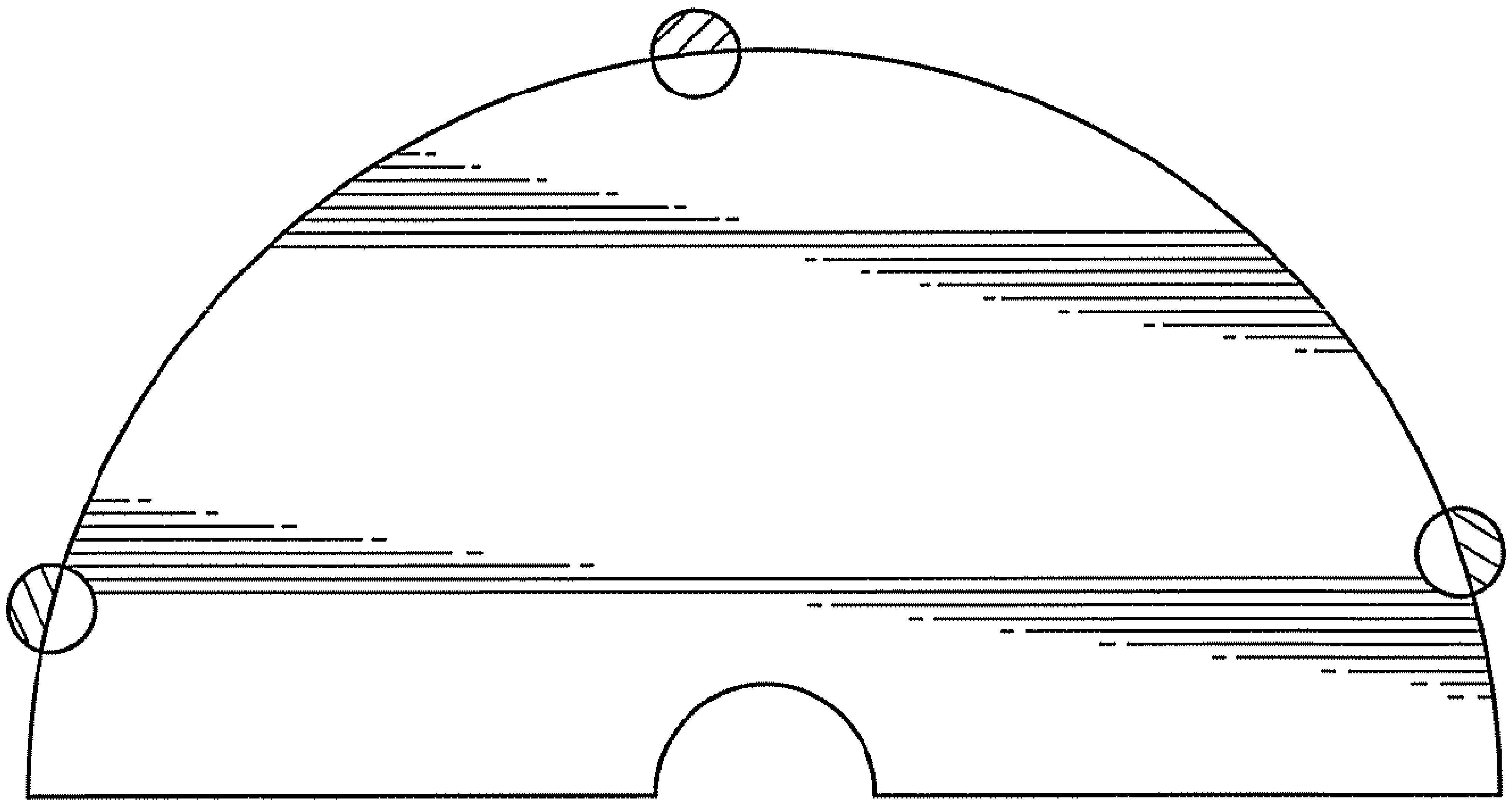


FIG. 8

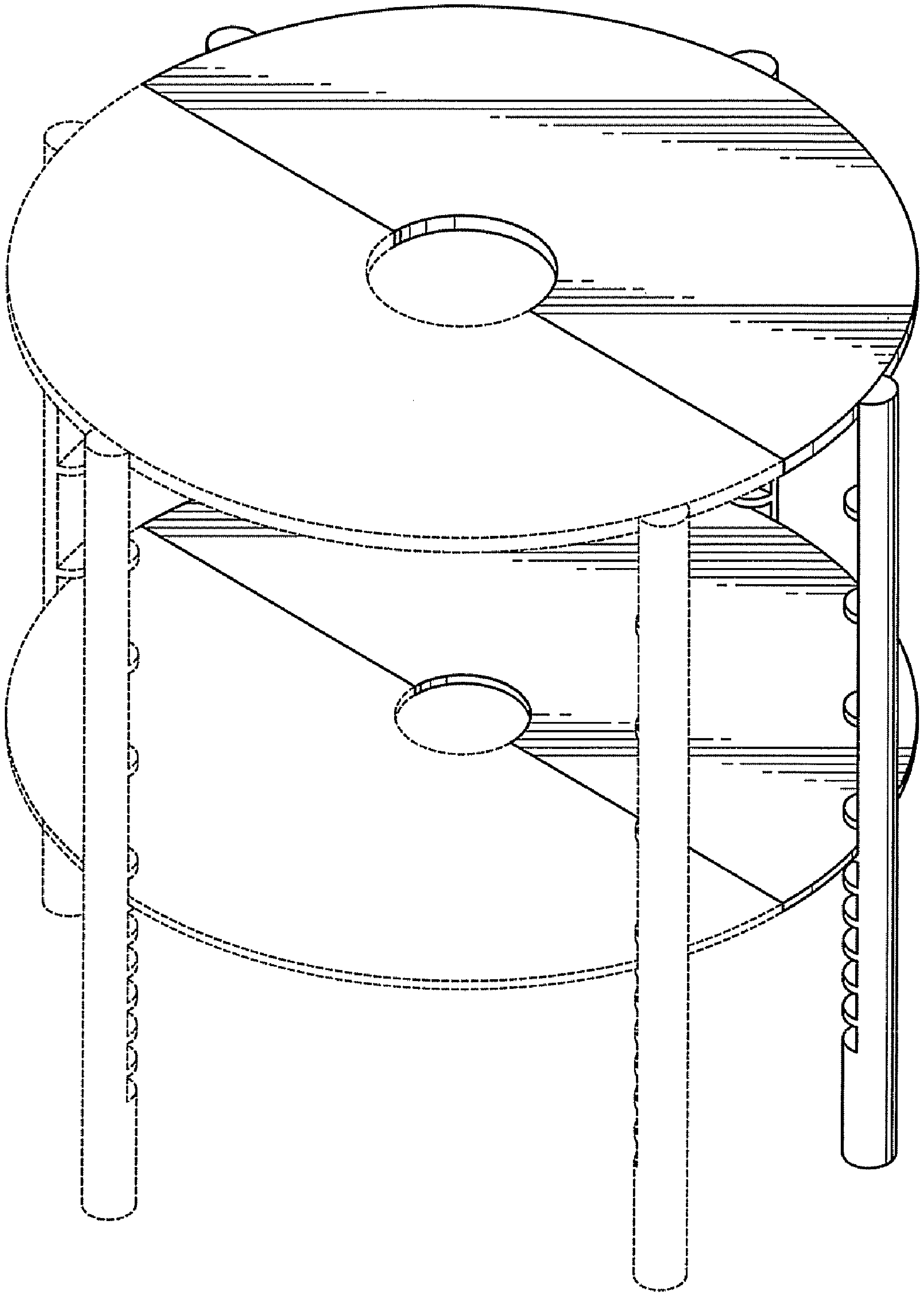


FIG. 9